Case name	**Sensor packaging**	
Dimensions in mm (L x W x H)	L = ca. 9 mm B = ca. 3 mm H = ca. 2 mm (without flex)	
Application	Temperature measurement	
RM process	3D-CSP, RMPD®	
Software	SolidWorks/ Orcad/Simulation software	
System	3D-CSP, RMPD® system	
Material	FDA USP Class VI biocompatible material	
Lead time (hours/days)	3 weeks from EDA design to prototype	
Costs	Typically 1 – 10 € @ 1000 pcs and larger qty., low invest/NRE	
Surface finish	R_a < 1 µm	
Mechanical properties	Soft or hard materials as needed for sensor packaging applications, Conductive lines made from Cu, NiCr, Au	
Thermal properties	Up to 180°C long term	
Any additional info	3D-CSP package integrating, e.g., sensors, ASICs, discretes. Interface to Flex, wire, wireless (3D-CSP antenna coil), connection plug board available	
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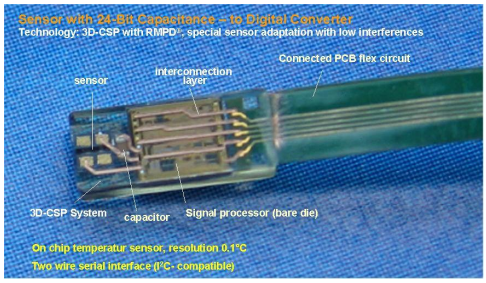

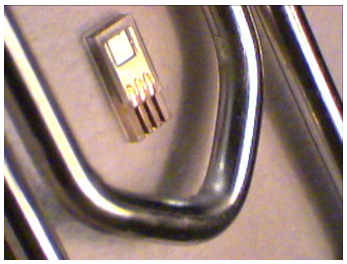
Pressure sensor packaging


SAW sensor package with fluidic interconnection


3D-CSP interface to slot connector with fluidic interface